

SPEC NO.		ISSUED DATE	2013.02.22	P	BY
PRODUCT NAME		VERSION	08	2013.02.26 文件管制章	
		PAGE	1/19		



SPECIFICATION

SPEC NO. : _____

PART NO. : _____

PRODUCT NAME : "NVG900A"

DESCRIPTION : Dielectric Antenna(29.8*6*5 mm)
ROHS Compliant Product

REVISION STATUS

VERSION	DATE	PAGE	REVISION DESCRIPTION	PREPARED	CHECKED	APPROVED
01	95.04.13	全	新制定	李靜怡	徐偉泓	楊才毅
02	95.08.16	全	新增 P8/12	李靜怡	徐偉泓	楊才毅
03	96.02.27	全	新增 P7/13 Reel 及 Carrier Tape	李靜怡	徐偉泓	楊才毅
04	96.08.23	全	新增 P4/23~P13/23 Gain and Efficiency 、 Power average gain 、 Antenna Pattern For Blue Tooth	林佳蓁	徐偉泓	楊才毅
05	97.06.24	全	修改 Recommend foot print for Evaluation Board Pad 尺寸原 3.8x2.2mm 改為 4.6x3mm	李靜怡	吳佳宗	楊才毅
06	2011.06.08	全	修改 P16/23 Shape and Dimension	徐嫻君	吳佳宗	徐偉泓
07	2013.01.31	P.17	Delivery mode	翁秀惠	陳菖賢	吳佳宗
08	2013.02.22	P.17	刪除前版修改內容	翁秀惠	陳菖賢	吳佳宗

Prepared By	Checked By	Approved By
翁秀惠	陳菖賢	吳佳宗



SPEC NO.		ISSUED DATE	2013.02.22	P	2013.02.26	BY
PRODUCT NAME		VERSION	08			
		PAGE	2/19			

PART NUMBER: @H95 - \$\$5

1 SCOPE

This specification covers the dielectric antenna for **880~960MHz, 1710~1990MHz**.

2 Name of the product

This product is named “Dielectric Antenna”.

3 Electrical characteristics

3-1 Electrical characteristics of antenna

The antenna has the electrical characteristics given in Table 1 under the standard installation conditions shown in the figure of Evaluation Board.

Table 1

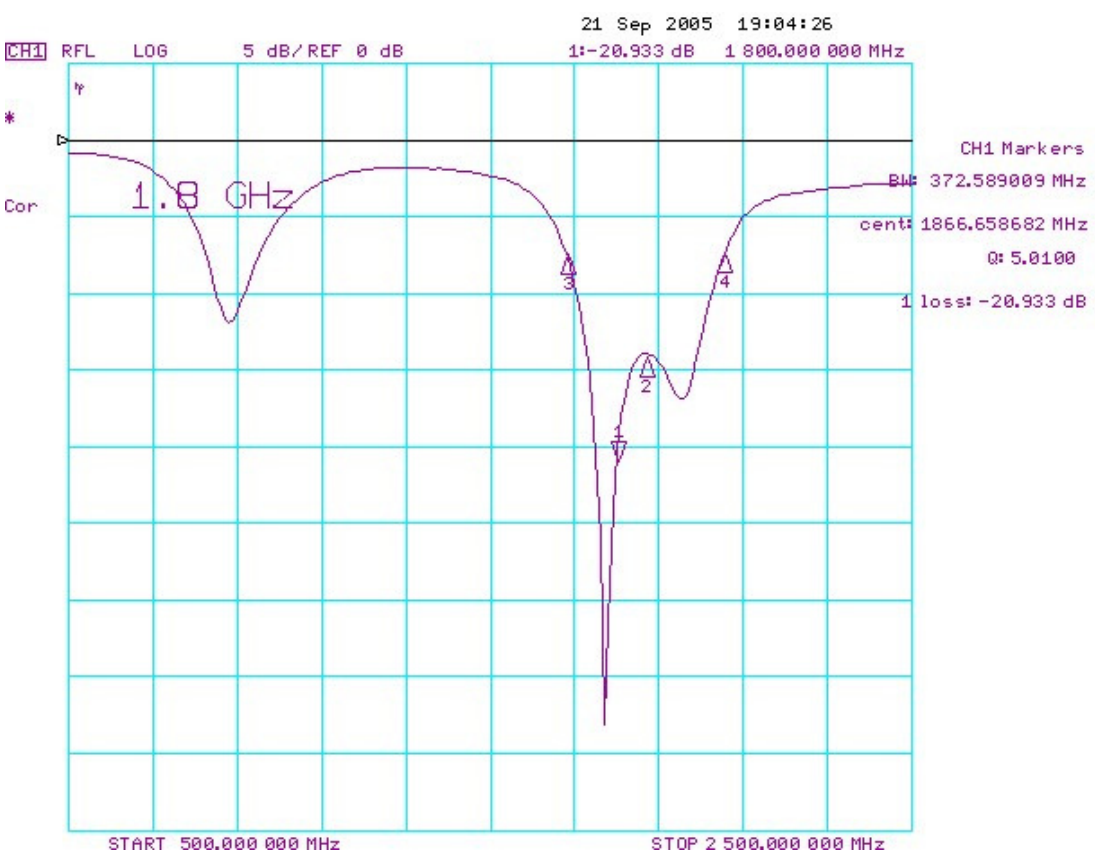
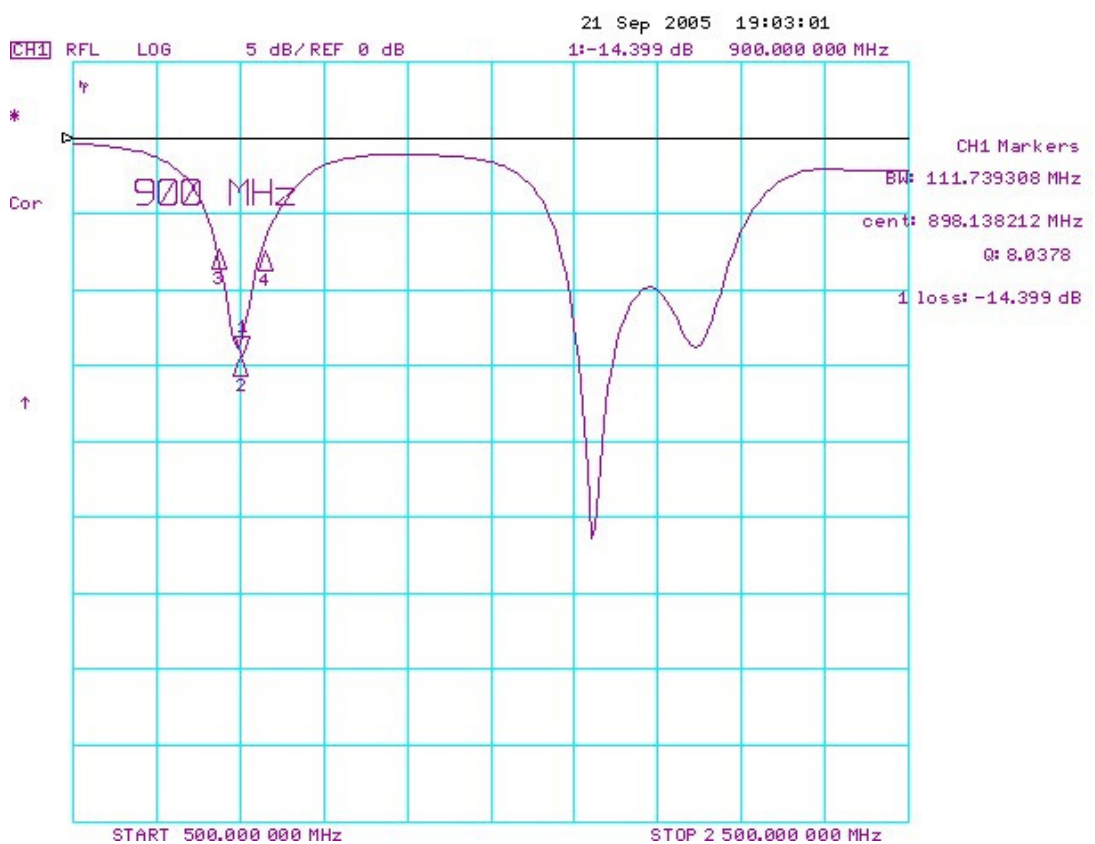
No	Parameter	Specification
1	Working Frequency	880~960 MHz , 1710~1990 MHz
2	Dimension	29.8*6*5 mm
3	VSWR	2.5 max (depends on the special environment)
4	Polarization	Linear
5	Impedance	50 Ω
6	Operating Temperature	-40~105℃
7	Termination	Ag (Environmentally-Friendly Pb Free)

* Actual value will depend on customer ground plane size

SPEC NO.		ISSUED DATE	2013.02.22	P 2013.02.26 文件管制章	BY
PRODUCT NAME		VERSION	08		
		PAGE	3/19		



S11 Response curve





SPEC NO.		ISSUED DATE	2013.02.22	P	BY
PRODUCT NAME		VERSION	08	<div>2013.02.26</div> <div>文件管制章</div>	
		PAGE	4/19		

Gain and Efficiency

GSM900

	Frequency (MHz)	Peak Gain (dBi)	Efficiency (%)
TX	880.2	-3.65	21.09
	890.2	-2.73	26.25
	902.4	-2.28	31.23
	914.8	-2.04	35.24
RX	925.2	-1.96	37.02
	935.2	-2.54	33.33
	947.4	-2.96	31.17
	959.8	-3.16	29.47

GSM1800

	Frequency (MHz)	Peak Gain (dBi)	Efficiency (%)
TX	1710.2	2.28	60.63
	1747.6	2.35	61.53
	1784.8	2.58	60.77
RX	1805.2	2.32	56.67
	1842.6	2.43	56.31
	1879.8	2.59	58.69

GSM1900

	Frequency (MHz)	Peak Gain (dBi)	Efficiency (%)
TX	1850.2	2.48	56.95
	1880.0	2.60	58.75
	1909.8	2.12	52.79
RX	1930.2	2.01	52.02
	1960.0	1.31	47.26
	1989.8	0.30	38.62



SPEC NO.		ISSUED DATE	2013.02.22	P	BY
PRODUCT NAME		VERSION	08	<div>2013.02.26</div> <div>文件管制章</div>	
		PAGE	5/19		

Power average gain

GSM900

Frequency (GHz)		Plane	Average Gain (dBi)
TX	880.2	XY plane	-7.133
		YZ plane	-9.766
		XZ plane	-6.101
	890.2	XY plane	-5.968
		YZ plane	-8.845
		XZ plane	-5.126
	902.4	XY plane	-4.898
		YZ plane	-8.892
		XZ plane	-4.350
	914.8	XY plane	-4.077
		YZ plane	-7.477
		XZ plane	-3.865
RX	925.2	XY plane	-3.599
		YZ plane	-7.202
		XZ plane	-3.732
	935.2	XY plane	-3.802
		YZ plane	-7.648
		XZ plane	-4.290
	947.4	XY plane	-3.788
		YZ plane	-7.843
		XZ plane	-4.579
	959.8	XY plane	-3.801
		YZ plane	-7.913
		XZ plane	-5.187



SPEC NO.		ISSUED DATE	2013.02.22	P	BY
PRODUCT NAME		VERSION	08		
		PAGE	6/19		

GSM1800

Frequency (GHz)		Plane	Average Gain (dBi)
TX	1710.2	XY plane	-2.648
		YZ plane	-4.661
		XZ plane	-1.687
	1747.6	XY plane	-2.529
		YZ plane	-4.696
		XZ plane	-1.207
	1784.8	XY plane	-2.685
		YZ plane	-4.687
		XZ plane	-0.888
RX	1805.2	XY plane	-3.193
		YZ plane	-4.911
		XZ plane	-1.105
	1842.6	XY plane	-3.468
		YZ plane	-4.753
		XZ plane	-1.145
	1879.8	XY plane	-3.745
		YZ plane	-4.131
		XZ plane	-1.430

GSM1900

Frequency (GHz)		Plane	Average Gain (dBi)
TX	1850.2	XY plane	-3.511
		YZ plane	-4.649
		XZ plane	-1.147
	1880.0	XY plane	-3.746
		YZ plane	-4.124
		XZ plane	-1.435



SPEC NO.		ISSUED DATE	2013.02.22	P	2013.02.26	BY
PRODUCT NAME		VERSION	08			
		PAGE	7/19			

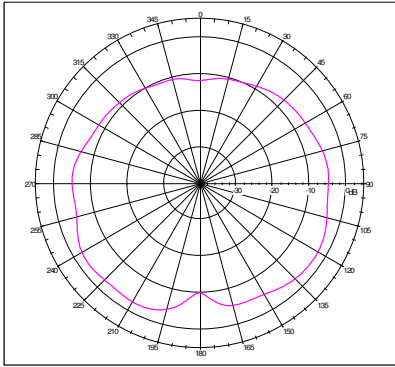
RX	1909.8	XY plane	-4.683
		YZ plane	-4.228
		XZ plane	-2.525
	1930.2	XY plane	-5.539
		YZ plane	-4.270
		XZ plane	-3.257
	1960.0	XY plane	-6.444
		YZ plane	-4.441
		XZ plane	-4.126
	1989.8	XY plane	-8.068
		YZ plane	-5.359
		XZ plane	-5.477

Antenna Pattern For Blue Tooth

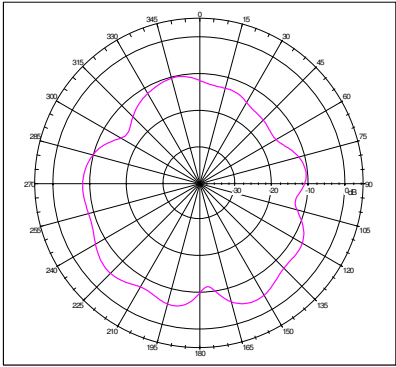
GSM900

Frequency :880.2 MHz

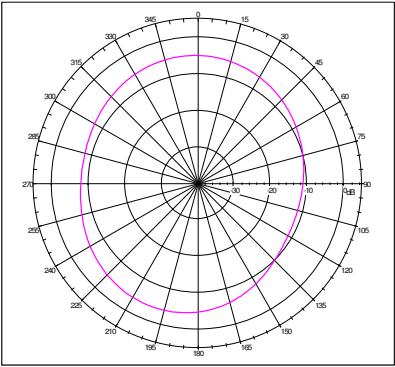
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain=-3.65 dBi; Total Radiating Efficiency: 21.09% @0.88020 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain=-3.65 dBi; Total Radiating Efficiency: 21.09% @0.88020 GHz

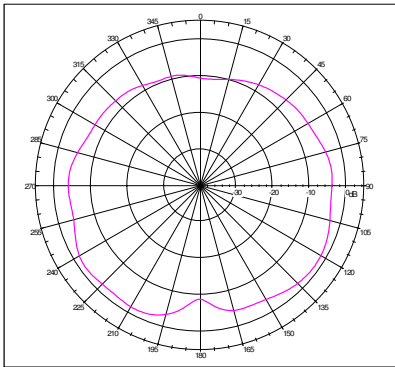


Far-field Power Distribution on X-Y Plane
Gain=-3.65 dBi; Total Radiating Efficiency: 21.09% @0.88020 GHz

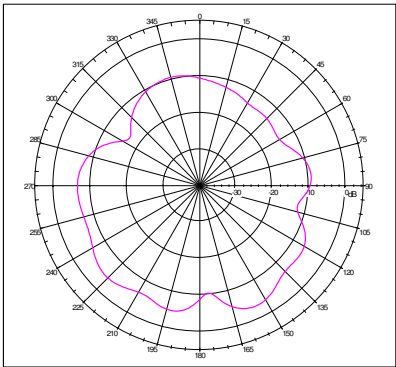


Frequency :890.2 MHz

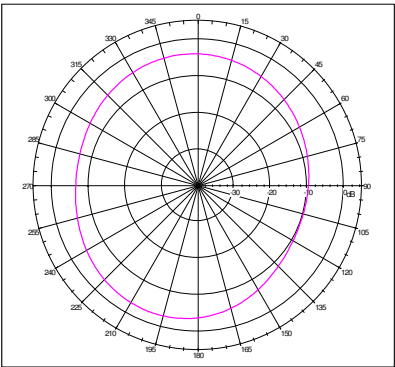
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain=-2.73 dBi; Total Radiating Efficiency: 26.25% @0.89020 GHz




Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain=-2.73 dBi; Total Radiating Efficiency: 26.25% @0.89020 GHz

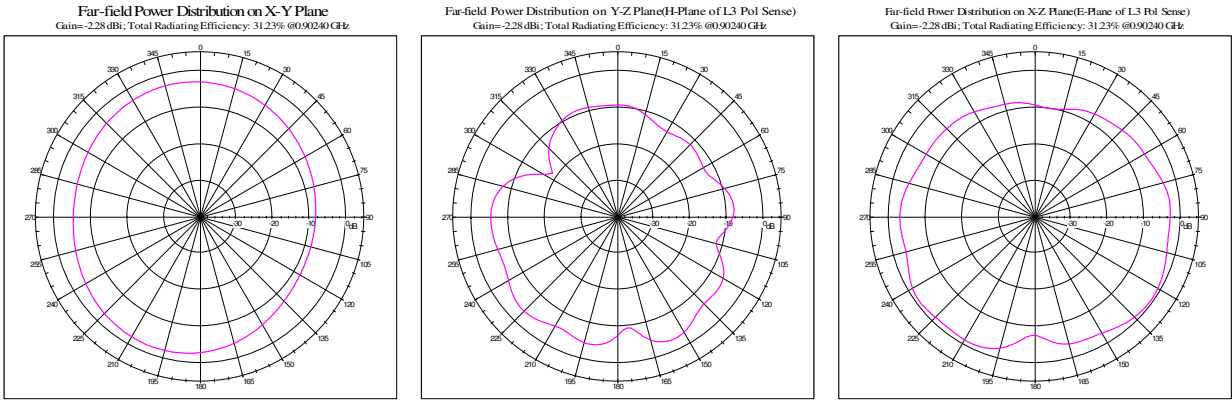


Far-field Power Distribution on X-Y Plane
Gain=-2.73 dBi; Total Radiating Efficiency: 26.25% @0.89020 GHz

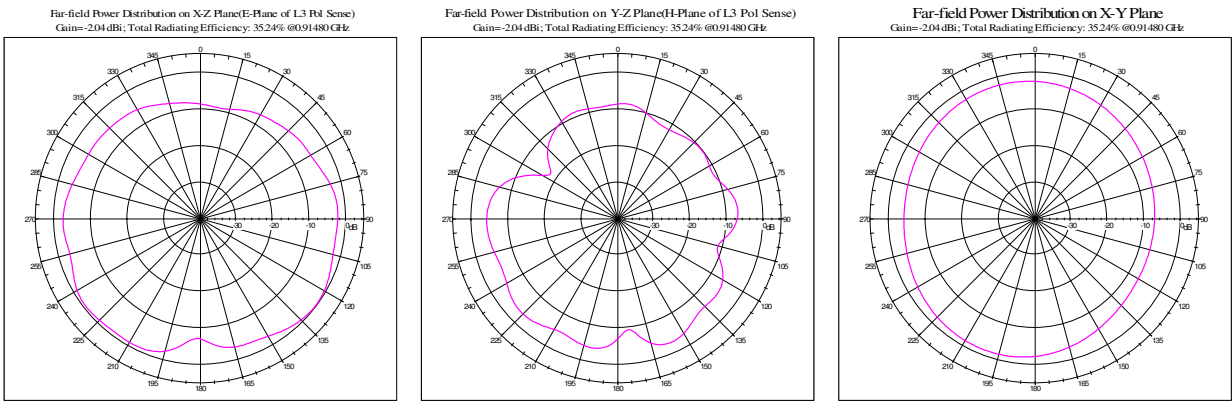


SPEC NO.		ISSUED DATE	2013.02.22	P	2013.02.26	BY
PRODUCT NAME		VERSION	08			
		PAGE	8/19			

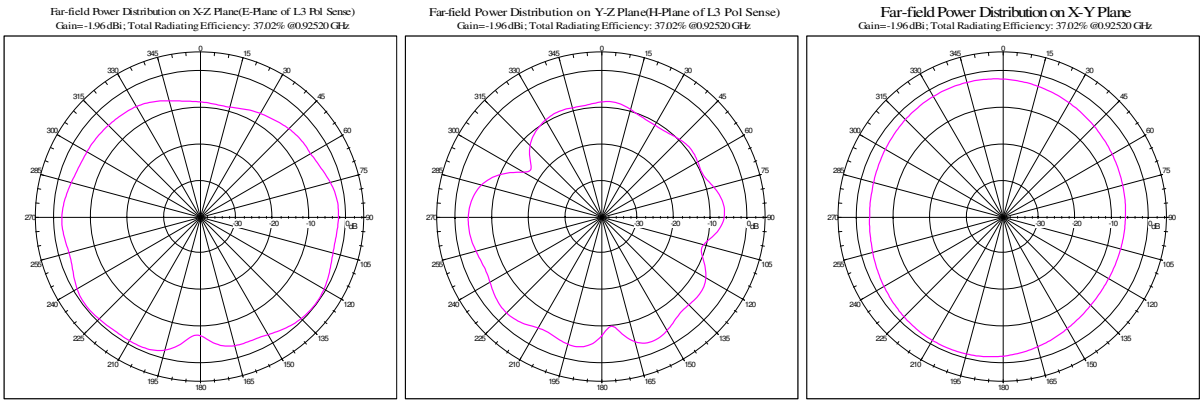
Frequency :902.4MHz




Frequency :914.8MHz



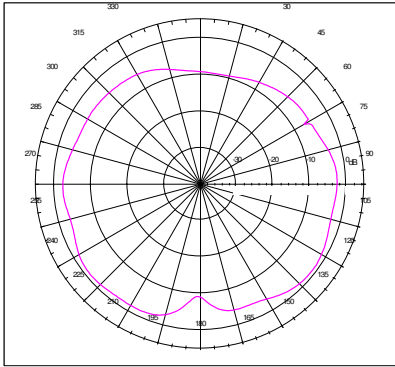
Frequency :925.2MHz



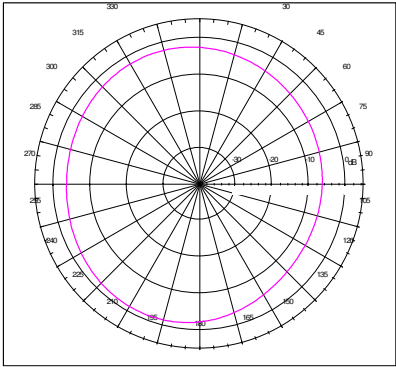
SPEC NO.		ISSUED DATE	2013.02.22	P	2013.02.26	BY
PRODUCT NAME		VERSION	08			
		PAGE	9/19			

Frequency :935.2MHz

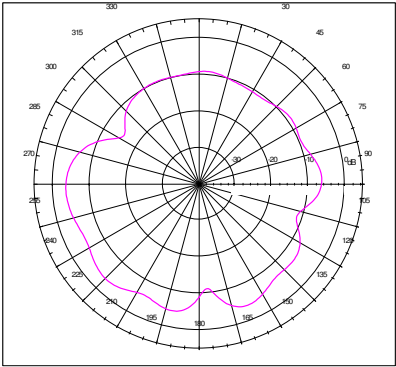
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain=-2.54 dBi; Total Radiating Efficiency: 33.33% @0.93520 GHz



Far-field Power Distribution on X-Y Plane
Gain=-2.54 dBi; Total Radiating Efficiency: 33.33% @0.93520 GHz

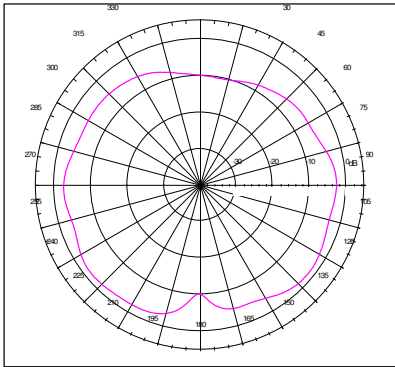


Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain=-2.54 dBi; Total Radiating Efficiency: 33.33% @0.93520 GHz

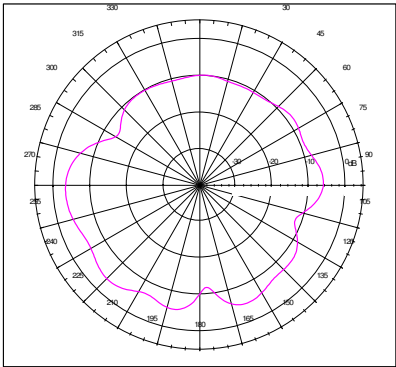


Frequency :947.4MHz

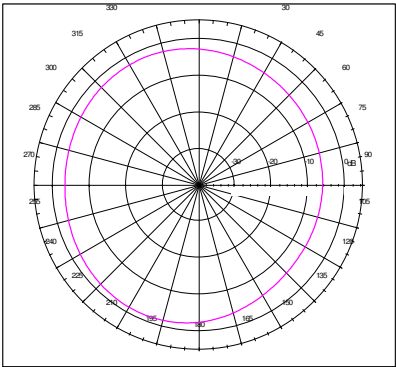
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain=-2.96 dBi; Total Radiating Efficiency: 31.17% @0.94740 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain=-2.96 dBi; Total Radiating Efficiency: 31.17% @0.94740 GHz

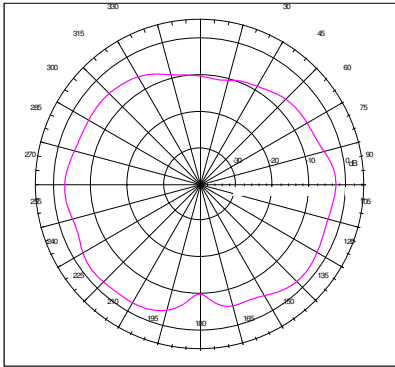


Far-field Power Distribution on X-Y Plane
Gain=-2.96 dBi; Total Radiating Efficiency: 31.17% @0.94740 GHz

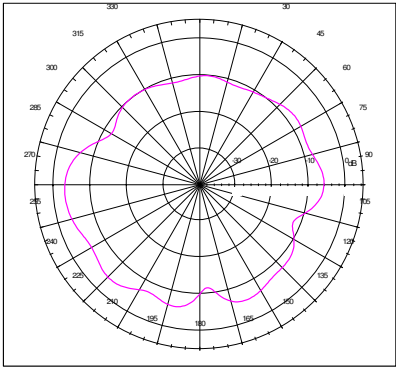


Frequency :959.8MHz

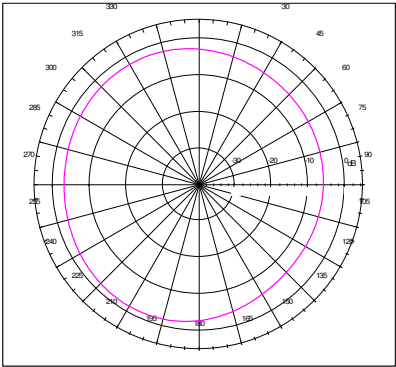
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain=-3.16 dBi; Total Radiating Efficiency: 29.47% @0.95980 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain=-3.16 dBi; Total Radiating Efficiency: 29.47% @0.95980 GHz



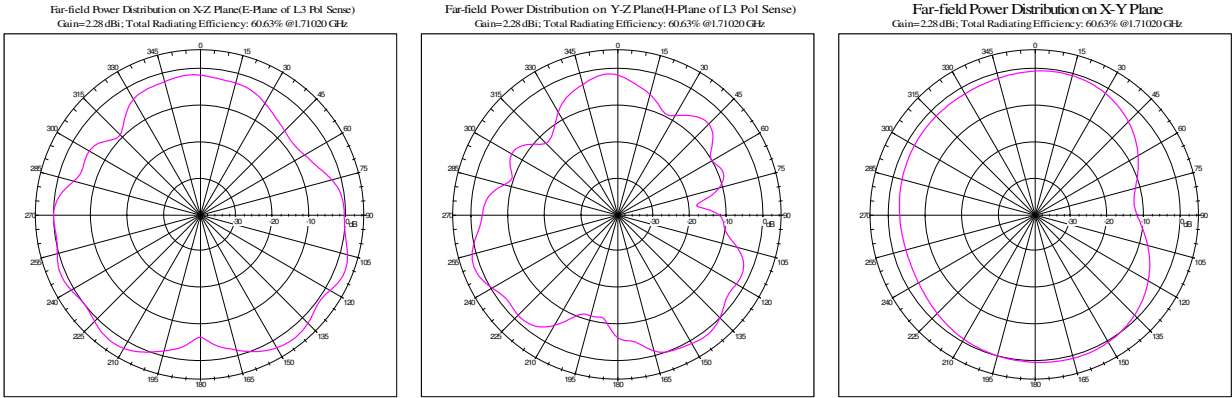
Far-field Power Distribution on X-Y Plane
Gain=-3.16 dBi; Total Radiating Efficiency: 29.47% @0.95980 GHz



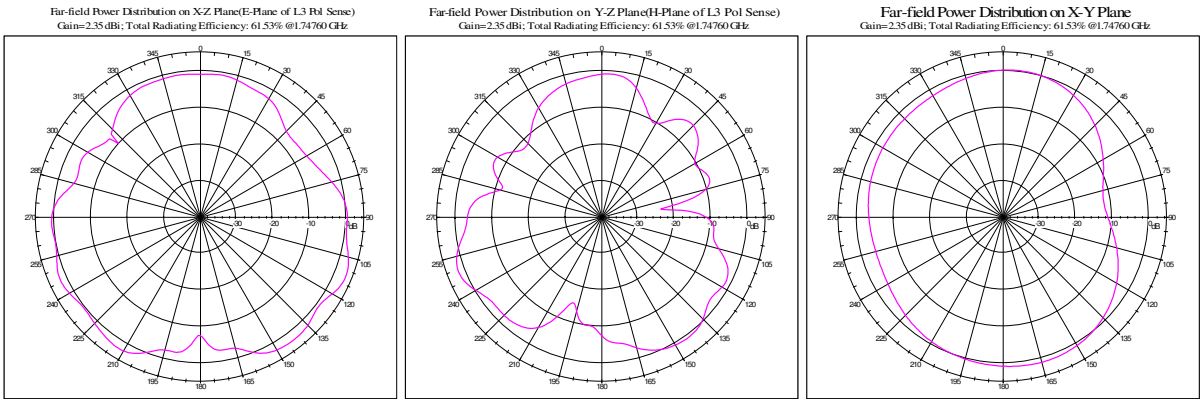
SPEC NO.		ISSUED DATE	2013.02.22	P	2013.02.26	BY
PRODUCT NAME		VERSION	08			
		PAGE	10/19			



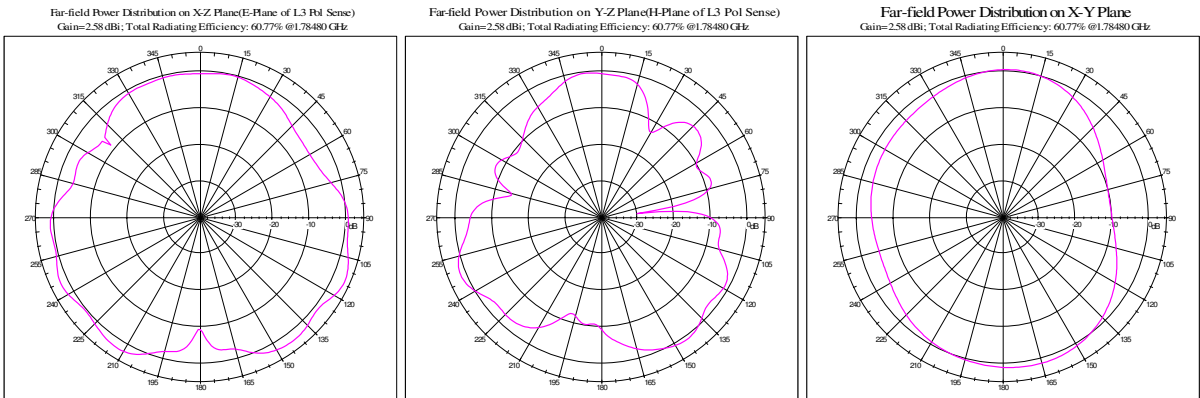
GSM1800
Frequency :1710.2 MHz



Frequency :1747.6 MHz



Frequency :1784.8 MHz

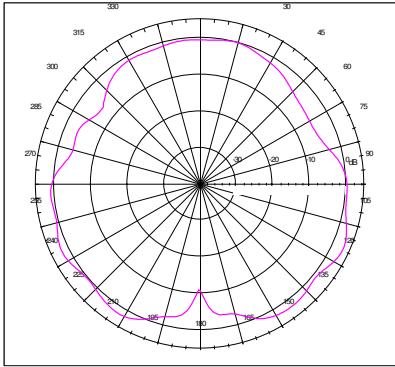


SPEC NO.		ISSUED DATE	2013.02.22	P	2013.02.26	BY
PRODUCT NAME		VERSION	08			
		PAGE	11/19			

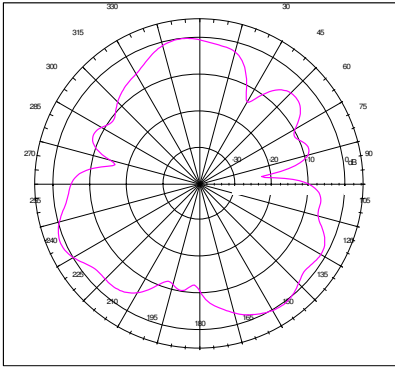


Frequency :1805.2 MHz

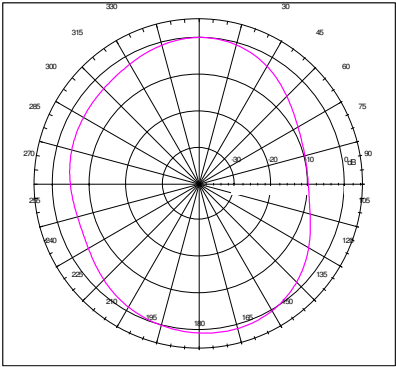
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain=2.32 dBi; Total Radiating Efficiency: 56.67% @1.80520 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain=2.32 dBi; Total Radiating Efficiency: 56.67% @1.80520 GHz

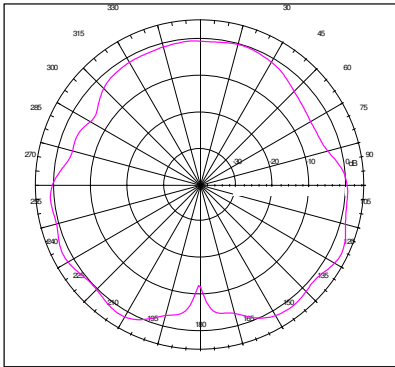


Far-field Power Distribution on X-Y Plane
Gain=2.32 dBi; Total Radiating Efficiency: 56.67% @1.80520 GHz

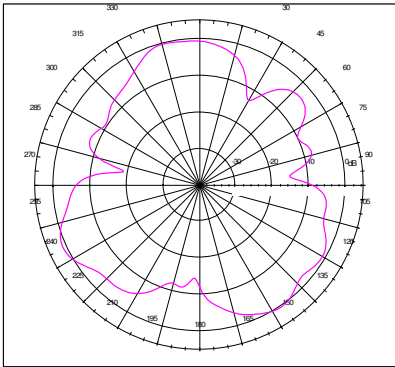


Frequency :1842.6 MHz

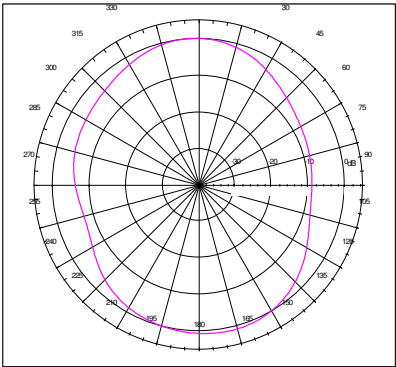
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain=2.42 dBi; Total Radiating Efficiency: 56.31% @1.84260 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain=2.42 dBi; Total Radiating Efficiency: 56.31% @1.84260 GHz

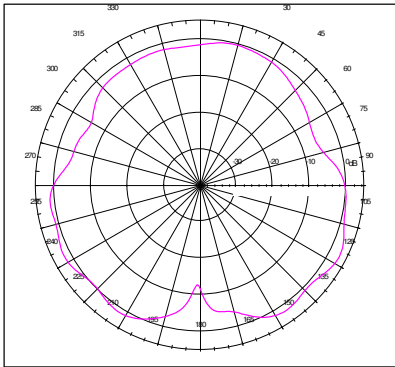


Far-field Power Distribution on X-Y Plane
Gain=2.42 dBi; Total Radiating Efficiency: 56.31% @1.84260 GHz

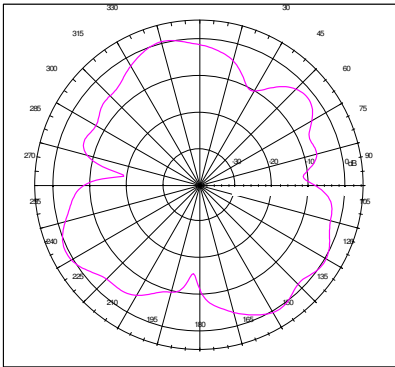


Frequency :1879.8 MHz

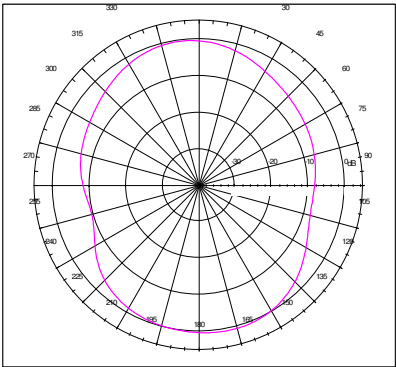
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain=2.59 dBi; Total Radiating Efficiency: 58.69% @1.87980 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain=2.59 dBi; Total Radiating Efficiency: 58.69% @1.87980 GHz



Far-field Power Distribution on X-Y Plane
Gain=2.59 dBi; Total Radiating Efficiency: 58.69% @1.87980 GHz



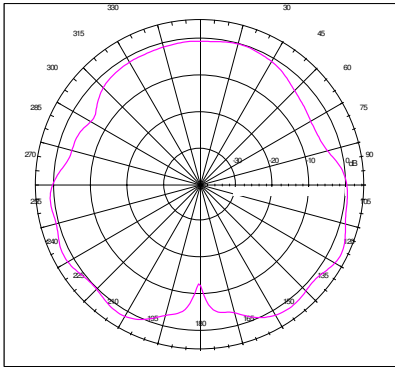


SPEC NO.		ISSUED DATE	2013.02.22	P	2013.02.26	BY
PRODUCT NAME		VERSION	08			
		PAGE	12/19			

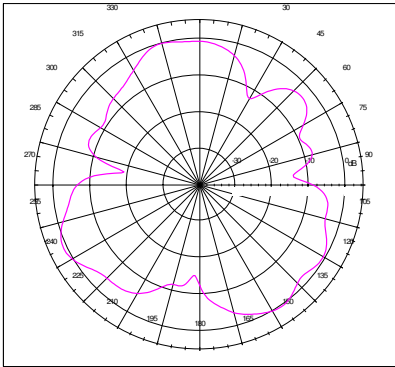
GSM1900

Frequency :1850.2 MHz

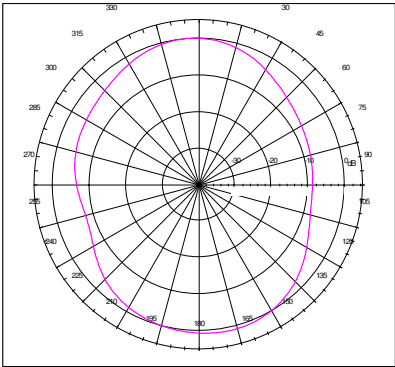
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain=2.48dBi; Total Radiating Efficiency: 56.95% @1.85020 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain=2.48dBi; Total Radiating Efficiency: 56.95% @1.85020 GHz

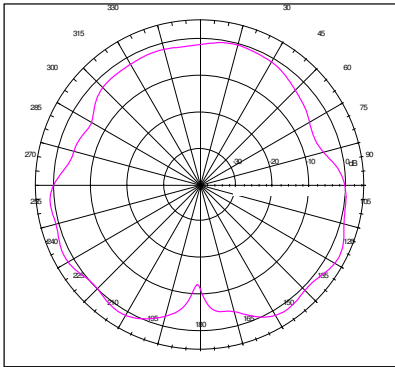


Far-field Power Distribution on X-Y Plane
Gain=2.48dBi; Total Radiating Efficiency: 56.95% @1.85020 GHz

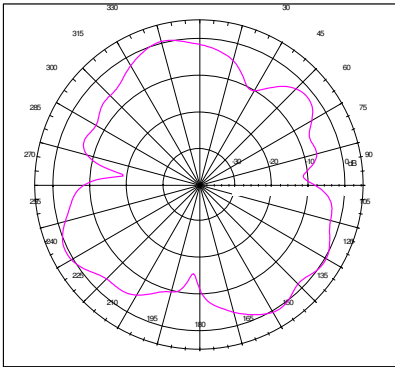


Frequency :1880.0 MHz

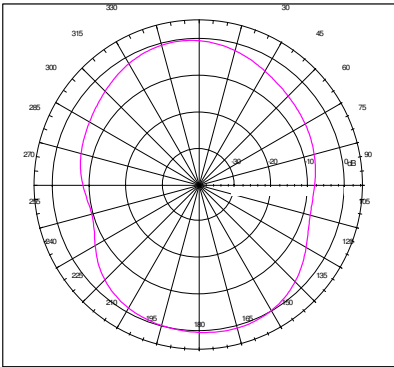
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain=2.60dBi; Total Radiating Efficiency: 58.75% @1.88000 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain=2.60dBi; Total Radiating Efficiency: 58.75% @1.88000 GHz

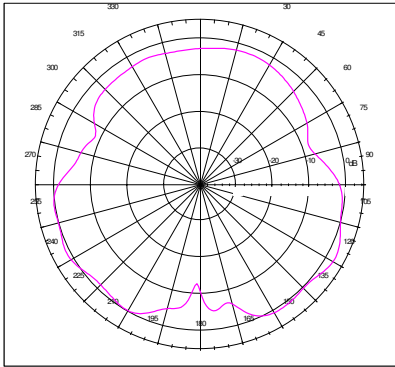


Far-field Power Distribution on X-Y Plane
Gain=2.60dBi; Total Radiating Efficiency: 58.75% @1.88000 GHz

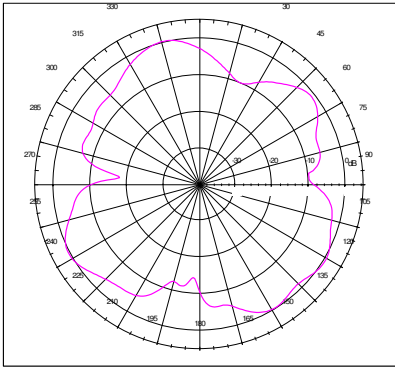


Frequency :1909.8 MHz

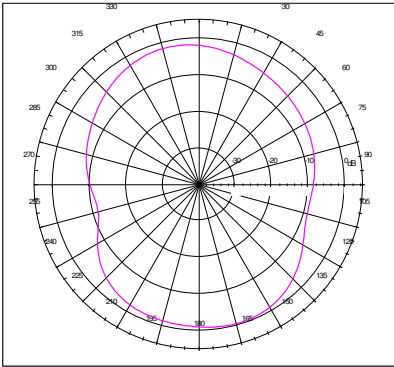
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain=2.12dBi; Total Radiating Efficiency: 52.79% @1.90980 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain=2.12dBi; Total Radiating Efficiency: 52.79% @1.90980 GHz



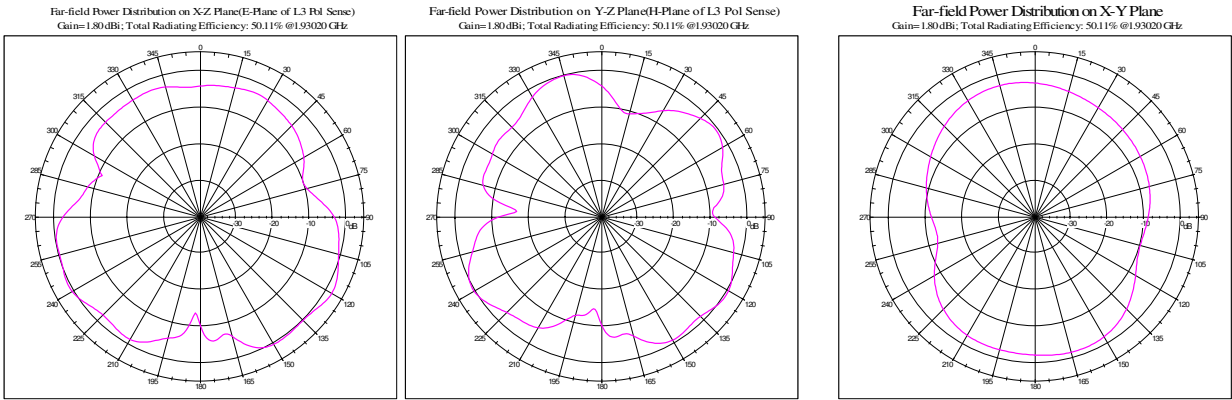
Far-field Power Distribution on X-Y Plane
Gain=2.12dBi; Total Radiating Efficiency: 52.79% @1.90980 GHz



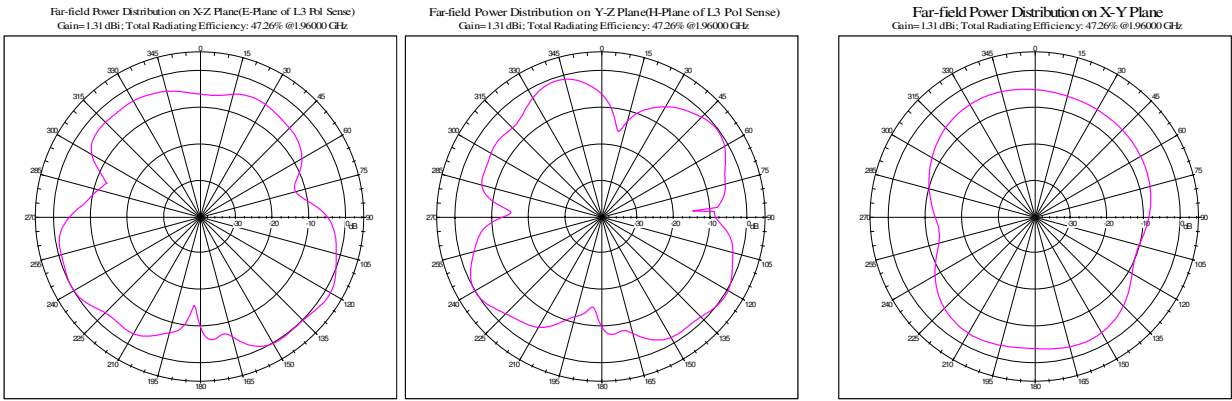


SPEC NO.		ISSUED DATE	2013.02.22	P	2013.02.26	BY
PRODUCT NAME		VERSION	08			
		PAGE	13/19			

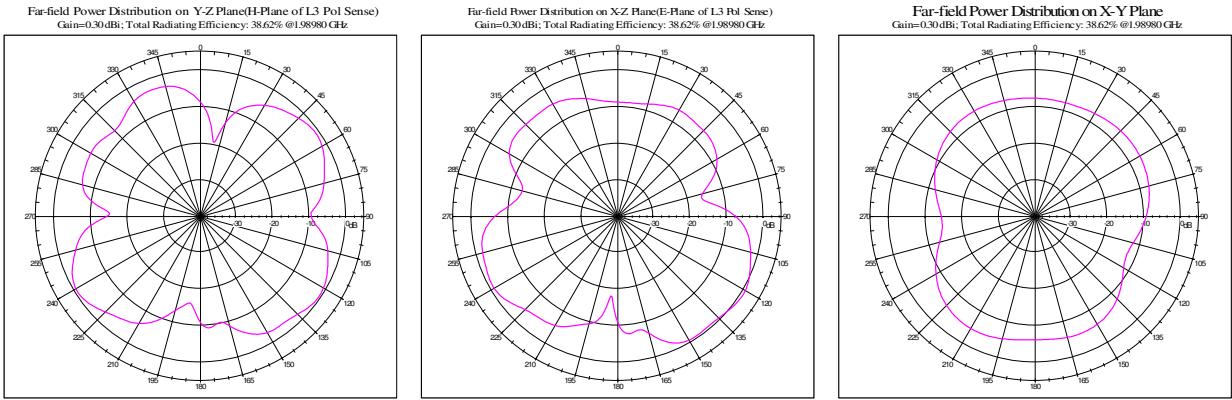
Frequency : 1930.2 MHz



Frequency : 1960.0 MHz



Frequency : 1989.8 MHz





SPEC NO.		ISSUED DATE	2013.02.22	P	2013.02.26	BY
PRODUCT NAME		VERSION	08			
		PAGE	14/19			

4 Environmental conditions

4-1 Operating conditions

The antenna has the electrical characteristics given in Tables 1 in the temperature range of -30°C to $+85^{\circ}\text{C}$ and under the environmental conditions of $+40^{\circ}\text{C}$ and 0-95 % r.h..

4-2 Storage temperature range

The storage temperature range of product is -40°C to $+100^{\circ}\text{C}$

5 Reliability tests

5-1. Low-temperature test

Expose the specimen to -30°C for 500 hours and then to normal temperature/humidity for 24 hours or more. After this test, examine its appearance and functions.

5-2 High-temperature test

Expose the specimen to $+85^{\circ}\text{C}$ for 500 hours and then to normal temperature/humidity for 24 hours or more. After this test, examine its appearance and functions.

5-3 High-temperature/high-humidity test

Subject the object to the environmental conditions of $+85^{\circ}\text{C}$ and 90-95% r.h. for 96 hours, then expose to normal temperature/humidity for 24 hours or more. After this test, examine its appearance and functions.

5-4 Thermal shock test

Subject the object to cyclic temperature change (-30°C , 30 minutes \rightarrow $+85^{\circ}\text{C}$, 30 minutes) for 5 cycles, the expose to normal temperature/humidity for 24 hours or more.

5-5 Vibration test

5-5-1 Sinusoidal vibration test

Subject the object to vibrations of 5 to 200 to 5Hz swept in 10 minutes, 4.5G at maximum (2mm amplitude), in X and Y directions for two hours each and in Z direction for four hours. After this test, examine its appearance functions.

5-5-2 Vibration test in packaged condition

Subject the object, which is packaged as illustrated, to vibrations of 15 to 60 to 15Hz swept in 6 minutes, 4G at maximum (2mm amplitude at maximum), applied in X, Y and Z directions for two hours each, i.e. six hours in total. After this test, examine its appearance and functions.



SPEC NO.		ISSUED DATE	2013.02.22	P	2013.02.26	BY
PRODUCT NAME		VERSION	08			
		PAGE	15/19			

5-6 Free fall test in packaged condition

Drop the object, which is packaged as illustrated, to a concrete surface from the height of 90 cm, on one corner, three edges and six faces once each, i.e. 10 times in total. After this test, examine its appearance and functions.

5-7. Soldering Heat Resistance Test:

After the lead pins of the unit are soaked in solder bath at $270 \pm 5^{\circ}\text{C}$ for 10 ± 0.5 seconds and then be left for more than 1 hour at $25 \pm 5^{\circ}\text{C}$ in less than 65% relative humidity.

5-8. Adhesion Test:

The device is subjected to be soldered on test PCB. Then apply 0.5Kg(5N) of force for 10 ± 1 seconds in the direction of parallel to the substrate. (the soldering should be done by reflow and be conducted with care so that the soldering is uniform and free of defect by stress such as heat shock) .

6 Inspection

As for the examination in the mass production, the receiving character of the ratio wave sent in a shield box from the standard antenna and VSWR are confirmed in the picking out examination.

7 Warranty

If any defect occurs from the product during proper use within a year after delivery, it will be repaired or replaced free of charge.

8 Other

Any question arising from this specification manual shall be solved by arrangement made by both parties.

9 Precautions for use

- Antenna pattern use a Ag electrode.
- Please don't use the corrosion gas (sulfur gas, chlorine gas) in the atmosphere.
- Please don't direct solder onto the gold electrode of Antenna pattern.

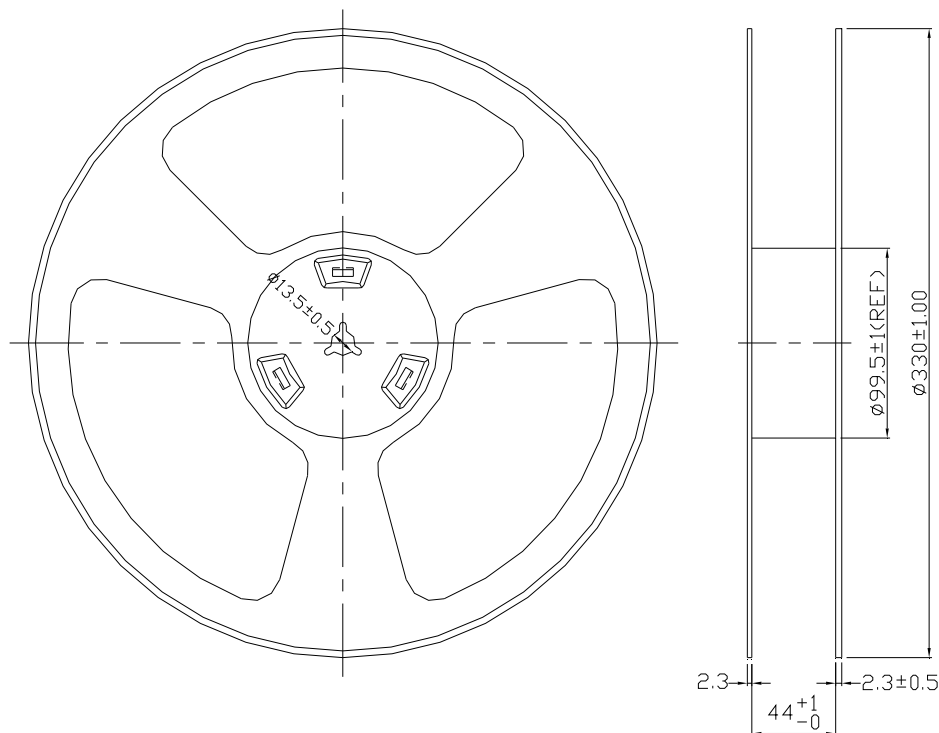


SPEC NO.		ISSUED DATE	2013.02.22	P	2013.02.26	BY
PRODUCT NAME		VERSION	08			
		PAGE	17/19			

Delivery mode

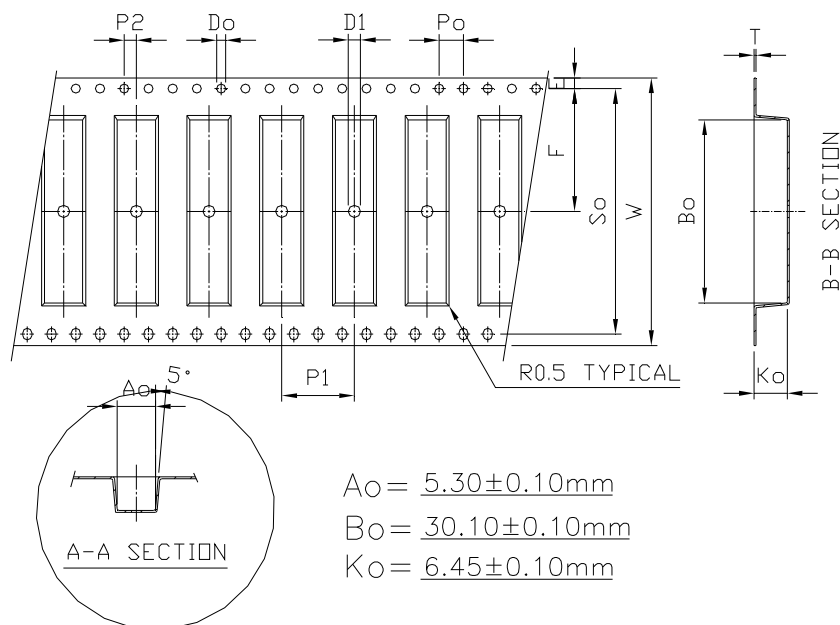
1 Blister tape to IEC 286-3 , polyester .

2 Pieces/tape : 450



Unit: mm

Symbol	Spec.
K1	—
Po	4.0 ± 0.10
P1	12.0 ± 0.10
P2	2.0 ± 0.15
Do	$1.5^{+0.1}_{+0}$
D1	2.0(Min)
E	1.75 ± 0.10
F	20.2 ± 0.10
10Po	40.0 ± 0.10
W	44.0 ± 0.30
T	0.30 ± 0.05
So	40.4 ± 0.10



Ao = 5.30 ± 0.10 mm

Bo = 30.10 ± 0.10 mm

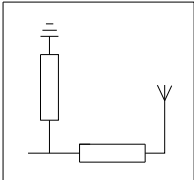
Ko = 6.45 ± 0.10 mm



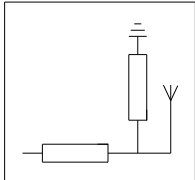
SPEC NO.		ISSUED DATE	2013.02.22	P	2013.02.26	BY
PRODUCT NAME		VERSION	08			
		PAGE	18/19			

Transmission line and matching

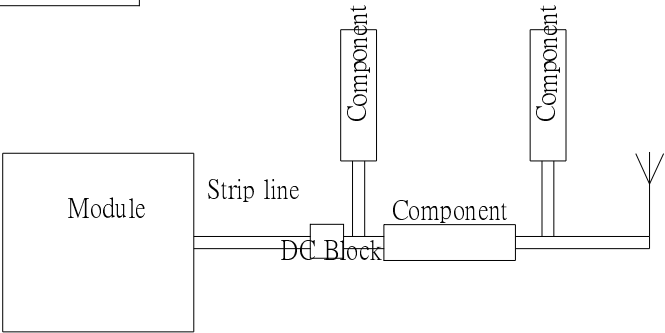
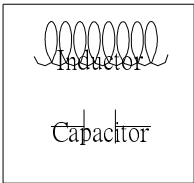
Typical config.1



Typical config.2

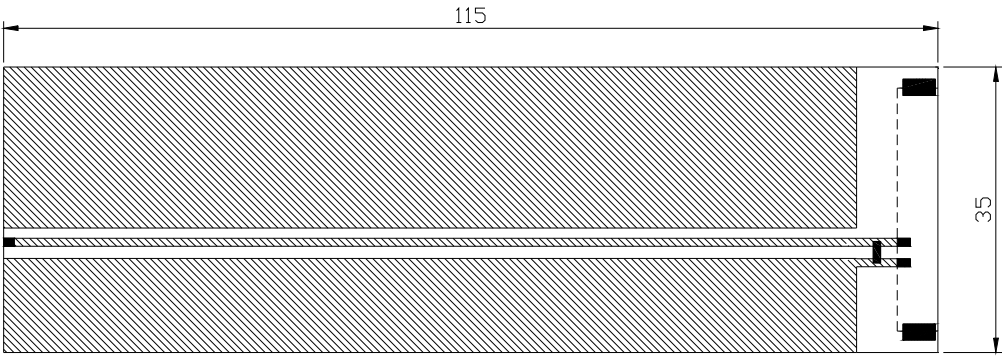


Component types



The matching network has to be individually designed using one,two or three components.

Test board dimensions

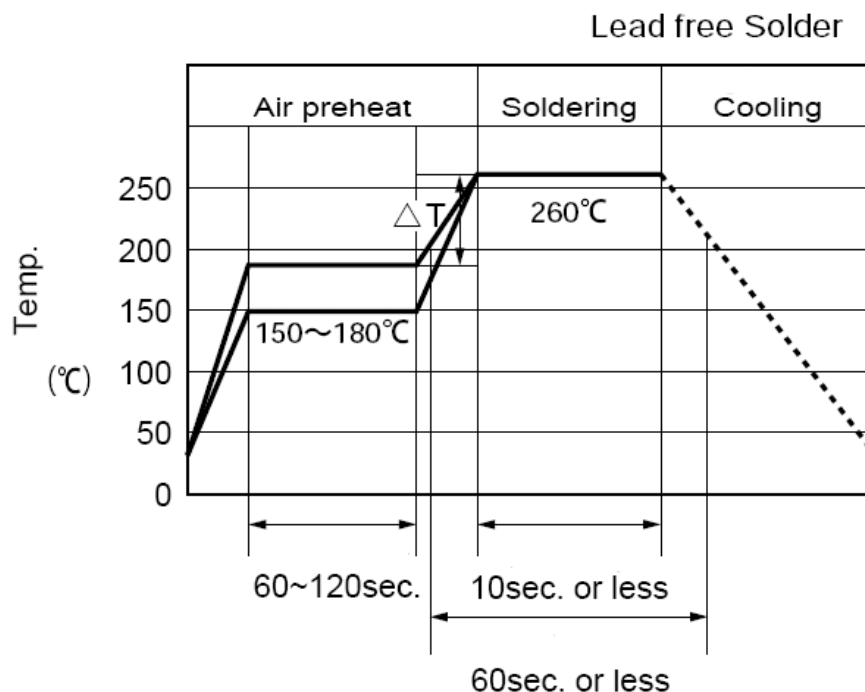


The testboard is designed for evaluation purposes for



SPEC NO.		ISSUED DATE	2013.02.22	P	2013.02.26	BY
PRODUCT NAME		VERSION	08			
		PAGE	19/19			

11.Recommended Reflow Temperature Profile



- (1) Time shown in the above figures is measured from the point when chip surface reaches temperature.
- (2) Temperature difference in high temperature part should be within 110°C.
- (3) After soldering, do not force cool, allow the parts to cool gradually.

*General attention to soldering:

- High soldering temperatures and long soldering times can cause leaching of the termination, decrease in adherence strength, and the change of characteristic may occur.
- For soldering, please refer to the soldering curves above. However, please keep exposure to temperatures exceeding 200°C to under 50 seconds.
- Please use a mild flux (containing less than 0.2wt% Cl). Also, if the flux is water soluble, be sure to wash thoroughly to remove any residue from the underside of components that could affect resistance.

Cleaning:

When using ultrasonic cleaning, the board may resonate if the output power is too high. Since this vibration can cause cracking or a decrease in the adherence of the termination, we recommend that you use the conditions below.

Frequency: 40 kHz max.

Output power: 20W/liter

Cleaning time: 5minutes max.